

P-Channel 30-V (D-S) MOSFET

Description

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low RDS(on) and to ensure minimal power loss and heat dissipation.

Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, and PCMCIA cards, cellular and cordless telephones.

Features

- Low rDS(on) provides higher efficiency and extends battery life
- Low thermal impedance copper lead frame SO-8 saves board space
- Fast switching speed
- RoHS compliant package

Package type: SO-8

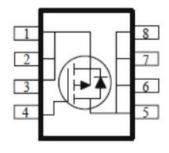
Packing & Order Information

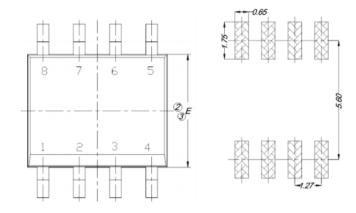
3,000/Reel

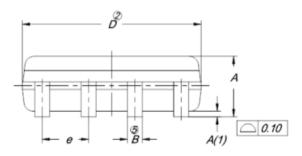


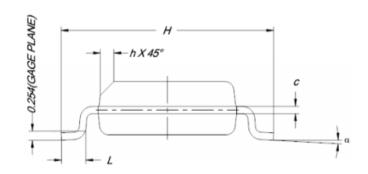
RoHS COMPLIANT

Graphic symbol









DI14	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	1.35	1.55	1.75		
A(1)	0.10	0.18	0.25		
В	0.38	0.45	0.51		
С	0.19	0.25			
D	4.80	4.90	5.00		
E	3.80	3.90	4.00		
е	1.27 BSC				
Н	5.80	6.00	6.20		
L	0.50	0.72	0.93		
α	0°	4°	8°		
h	0.25	0.38	0.50		



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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T _A =25°C unless otherwise specified)					
Symbol	Parameter	Value	Unit		
V_{DS}	Drain-Source Voltage	-30	V		
V_{GS}	Gate-Source Voltage	±25	V		
I_D	Continuous Drain Current ^a (T _A =25°C)	-11.5	A		
	Continuous Drain Current ^a (T _A =70°C)	-9.3	A		
I_{DM}	Pulsed Drain Current ^b	-50	A		
Is	Continuous Source Current (Diode Conduction) ^a	±4.3	A		
PD	Power Dissipation ^a (T _A =25°C)	3.1	W		
	Power Dissipation ^a (T _A =70°C)	2.2	W		
T _J /T _{STG}	Operating Junction and Storage Temperature	-55 to +150	°C		

Thermal characteristics (Tc=25°C unless otherwise noted)						
Symbol	Parameter Maximum Uni					
R _{θJA}	Maximum Junction-to-Ambient C/W ^a (t <= 10 sec)	40	°C/W			
	Maximum Junction-to-Ambient C/W ^a (Steady-State)	80	C/W			

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Static						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1.0			V
I _{GSS}	Gate-Body Leakage	$V_{DS}=0~V$, $V_{GS}=\pm25~V$			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24 \ V$, $V_{GS} = 0 \ V$ $V_{DS} = -24 \ V$, $V_{GS} = 0 \ V$, $T_{J} = 55 ^{\circ}C$			-1 -25	uA
I _{D(on)}	On-State Drain Current	$V_{DS} = 5 \text{ V}, V_{Gs} = 10 \text{ V}$	-5.75			A
R _{DS(on)}	Drain-Source On-Resistance	$V_{DS} = 10 \text{ V}, I_{D} = -9.2 \text{ A}$ $V_{DS} = -4.5 \text{ V}, I_{D} = -7.5 \text{ A}$			13 19	mΩ
g fs	Forward Tranconductance	$V_{GS} = -15 \text{ V}, I_D = -9.2 \text{ A}$		40		S
V _{SD}	Diode Forward Voltage	$I_S = -2.2 \text{ A}$, $V_{GS} = 0 \text{ V}$		-0.7		V

Dynamic						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
Q_g	Total Gate Charge	$V_{DS} = -15 \text{ V}$, $I_{D} = -9.2 \text{ A}$, $V_{GS} = -4.5 \text{ V}$		42		nC
Q_{gs}	Gate-Source Charge			13		nC
Qgd	Gate-Drain Charge			20		nC



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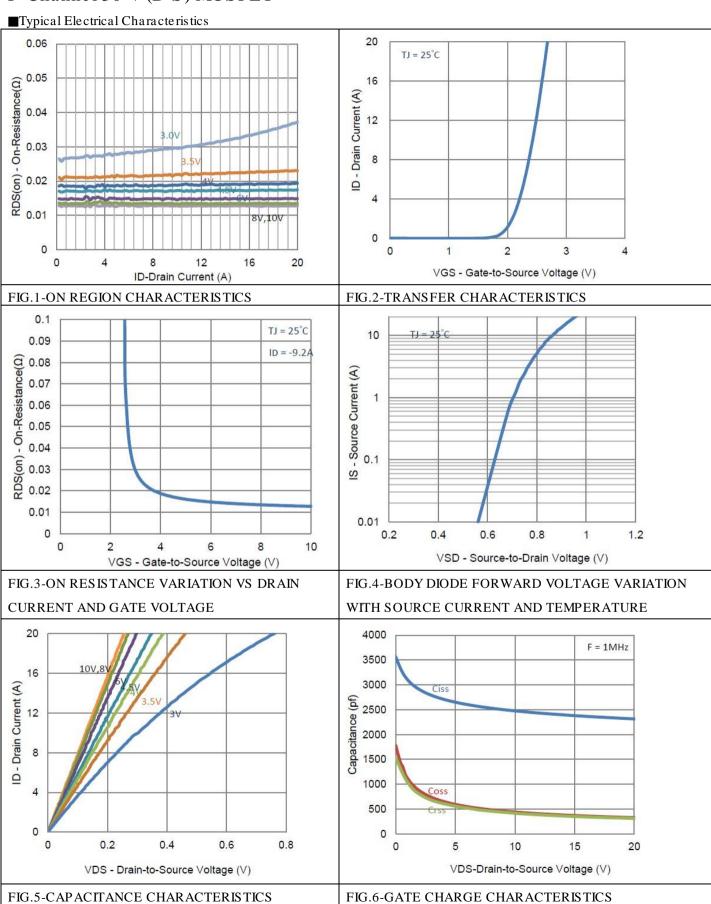
Dynamic						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time			9		ns
t _r	Rise Time	$I_D = -9.2 \text{ A}, R_L = 1.7 \Omega,$ $V_{GEN} = -10 \text{ V}, R_{GEN} = 6 \Omega$ $V_{DS} = -15 \text{ V}$		48		ns
$t_{\rm d(off)}$	Turn-Off Delay Time			104		ns
tf	Fall Time			59		ns
C _{ISS}	Input Capacitance	$V_{DS} = -15 \text{ V}$ - f = 1 MHz , $V_{GS} = 0 \text{ V}$		2380		pF
Coss	Output Capacitance			369		pF
Crss	Reverse Transfer Capacitance			350		pF

Notes

- a. Pulse test: $PW \le 300us duty cycle \le 2\%$.
- b. Guaranteed by design, not subject to production testing.



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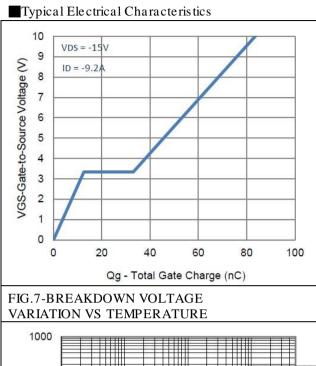


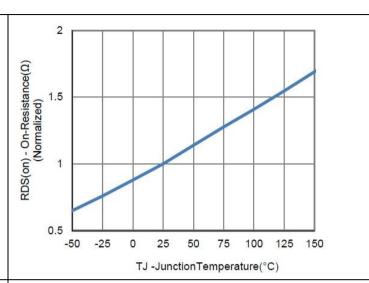
MS 48 P 25

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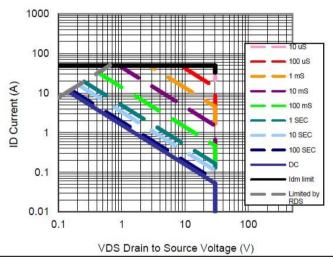


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

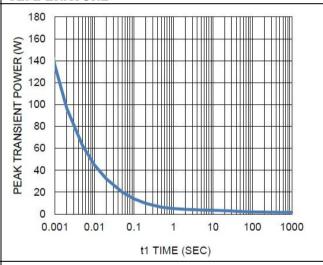
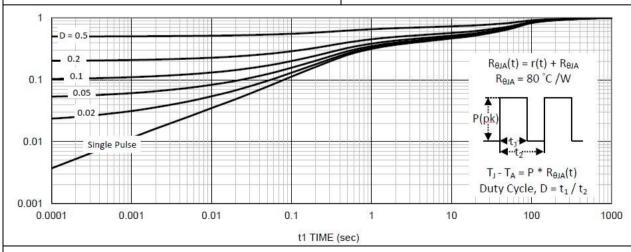


FIG.9-MAXIMUM SAFE OPERATING AREA

 $\begin{aligned} & \textbf{FIG.10-MAXIMUM DRAIN CURRENT VS CASE} \\ & \textbf{TEMPERATURE} \end{aligned}$





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